	Hits	Search Text	DBs
2	1	((print$4 near9 (wiring or circuit$4) near9 board) or PCB or ((circuit$4 or wiring) near9 board)) and (((FR$3 near6 insulat$3) or (non$3copper near6 clad$3 near9 laminate)) same (via or holes or through$5hole or thru$5hole) same (fill$4 or deposit$4) same ((capacitor near9 paste) or BaTi$2O$2 or (ceramic near9 dielectric near9 powder))) and ((PCB or PWB or (circuit$5 near9 board)) same ((copper or Cu) near16 (foil or layer or film)) same bottom same (upper or top) same electrode same (circuit$4 near17 signal) same ((resin near9 (copper or Cu)) or RCC) same laminat$4) and (plat$4 or electro$4plat$4)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
3	2	((print$4 near9 (wiring or circuit$4) near9 board) or PCB or ((circuit$4 or wiring) near9 board)) and (((FR$3 near6 insulat$3) or (non$3copper near6 clad$3 near9 laminate)) same (via or holes or through$5hole or thru$5hole) same (fill$4 or deposit$4) same ((capacitor near9 paste) or BaTi$2O$2 or (ceramic near9 dielectric near9 powder))) and ((PCB or PWB or (circuit$5 near9 board)) same ((copper or Cu) near16 (foil or layer or film)) same bottom same (upper or top) same electrode same (circuit$4 near17 signal)) and (((resin near9 (copper or Cu)) or RCC) same laminat$4) and (plat$4 or electro$4plat$4)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
4	2	((print$4 near9 (wiring or circuit$4) near9 board) or PCB or ((circuit$4 or wiring) near9 board)) and (((FR$3 near6 insulat$3) or ((non$3copper or insulat$4) near6 clad$3 near9 laminate)) same (via or holes or through$5hole or thru$5hole) same (fill$4 or deposit$4) same ((capacitor near9 paste) or BaTi$2O$2 or (ceramic near9 dielectric near9 powder))) and ((PCB or PWB or (circuit$5 near9 board)) same ((copper or Cu) near16 (foil or layer or film)) same bottom same (upper or top) same electrode same (circuit$4 near17 signal)) and (((resin near9 (copper or Cu)) or RCC) same laminat$4) and (plat$4 or electro$4plat$4)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
5	2	((print$4 near9 (wiring or circuit$4) near9 board) or PCB or ((circuit$4 or wiring) near9 board)) and (((FR$3 near6 insulat$3) or ((non$3copper or insulat$4) near6 clad$3 near9 laminate)) same (via or holes or through$5hole or thru$5hole)) and ((through$4hole or hole or via) same (fill$4 or deposit$4) same ((capacitor near9 paste) or BaTi$2O$2 or (ceramic near9 dielectric near9 powder))) and ((PCB or PWB or (circuit$5 near9 board)) same ((copper or Cu) near16 (foil or layer or film))) and (((resin same (copper or Cu)) or RCC) same laminat$4) and (plat$4 or electro$4plat$4) and electrode	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
6	5	((print$4 near9 (wiring or circuit$4) near9 board) or PCB or ((circuit$4 or wiring) near9 board)) and (((FR$3 near6 insulat$3) or ((non$3copper or insulat$4) near22 laminate)) same (via or holes or through$5hole or thru$5hole)) and ((through$4hole or hole or via) same (fill$4 or deposit$4) same ((capacitor near19 (powder or paste)) or BaTi$20$2 or (ceramic near9 dielectric near9 (paste or powder)))) and ((PCB or PWB or (circuit$5 near9 board)) same ((copper or Cu) near16 (foil or layer or film))) and (((resin same (copper or Cu)) or RCC)) and (plat$4 or electro$4plat$4) and electrode	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
7	2	((print$4 near9 (wiring or circuit$4) near9 board) or PCB or ((circuit$4 or wiring) near9 board)) and (((FR$3 near6 insulat$3) or ((non$3copper or insulat$4) near6 clad$3 near9 laminate)) same (via or holes or through$5hole or thru$5hole) same (fill$4 or deposit$4) same ((capacitor near9 paste) or BaTi$2O$2 or (ceramic near9 dielectric near9 powder))) and ((PCB or PWB or (circuit$5 near9 board)) same ((copper or Cu) near16 (foil or layer or film)) same bottom same (upper or top) same electrode same (circuit$4 near17 signal)) and (((resin same (copper or Cu)) or RCC) same laminat$4) and (plat$4 or electro$4plat$4)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
8	2	((print$4 near9 (wiring or circuit$4) near9 board) or PCB or ((circuit$4 or wiring) near9 board)) and (((FR$3 near6 insulat$3) or ((non$3copper or insulat$4) near6 clad$3 near9 laminate)) same (via or holes or through$5hole or thru$5hole)) and ((through$4hole or hole or via) same (fill$4 or deposit$4) same ((capacitor near9 paste) or BaTi$20$2 or (ceramic near9 dielectric near9 powder))) and ((PCB or PWB or (circuit$5 near9 board)) same ((copper or Cu) near16 (foil or layer or film)) same bottom same (upper or top) same electrode same (circuit$4 near17 signal)) and (((resin same (copper or Cu)) or RCC) same laminat$4) and (plat$4 or electro$4plat$4)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
9	4	((print$4 near9 (wiring or circuit$4) near9 board) or PCB or ((circuit$4 or wiring) near9 board)) and (((FR$3 near6 insulat$3) or ((non$3copper or insulat$4) near22 laminate)) same (via or holes or through$5hole or thru$5hole)) and ((through$4hole or hole or via) same (fill$4 or deposit$4) same ((capacitor near9 paste) or BaTi$2O$2 or (ceramic near9 dielectric near9 powder))) and ((PCB or PWB or (circuit$5 near9 board)) same ((copper or Cu) near16 (foil or layer or film))) and (((resin same (copper or Cu)) or RCC) same laminat$4) and (plat$4 or electro$4plat$4) and electrode	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
10	8	((print$4 near9 (wiring or circuit$4) near9 board) or PCB or ((circuit$4 or wiring) near9 board)) and (((FR$3 near6 insulat$3) or ((non$3copper or insulat$4) near22 laminat$5)) same (via or holes or through$5hole or thru$5hole)) and ((through$4hole or hole or via) same (fill$4 or deposit$4) same ((capacitor near19 (powder or paste)) or BaTi$20$2 or (capacitor near16 dielectric) or (ceramic near9 dielectric near9 (paste or powder)))) and ((PCB or PWB or (circuit$5 near9 board)) same ((copper or Cu) near16 (foil or layer or film))) and (((resin same (copper or Cu)) or RCC)) and (plat$4 or electro$4plat$4) and electrode	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
11	24	(((print$4 near9 (wiring or circuit$4) near9 board) or PCB or ((circuit$4 or wiring) near9 board)) same (via or hole or through$4hole or thru$4hole)) and (((FR$3 near6 insulat$3) or ((non$3copper or insulat$4) near22 laminat$5) or (laminat$3 near9 insulat$4)) same (via or holes or through$5hole or thru$5hole)) and ((through$4hole or hole or via) same (fill$4 or deposit$4 or form$4) same ((capacitor near19 (powder or paste or material)) or BaTi$2O$2 or (capacitor near16 dielectric) or (ceramic near12 dielectric near16 (paste or powder or material)))) and ((PCB or PWB or (circuit$5 near9 board)) same ((copper or Cu) near16 (foil or layer or film or laminat$4)) same (electrode or wiring or circuit$4)) and (((resin same (copper or Cu)) or RCC)) and (plat$4 or electro$4plat$4) and electrode	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
12	24	(((print$4 near9 (wiring or circuit$4) near9 board) or PCB or ((circuit$4 or wiring) near9 board)) same (via or hole or through$4hole or thru$4hole)) and (FR4 near12 (dielectric or insulator) near16 (board or panel or core or substrate or PCB) near22 ceramic)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
13	11	(((print$4 near9 (wiring or circuit$4) near9 board) or PCB or ((circuit$4 or wiring) near9 board)) same (via or hole or through$4hole or thru$4hole)) and (FR4 same (dielectric or insulat$4) same (board or panel or core) same ceramic same core same PCB)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
14	8	(((print$4 near9 (wiring or circuit$4) near9 board) or PCB or ((circuit$4 or wiring) near9 board)) same (via or hole or through$4hole or thru$4hole)) and (((barium near9 titanate) or BaTiO) same (powder or paste or material) same particle same diameter same (polymer or resin or epoxy))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
15	4	(((print$4 near9 (wiring or circuit$4) near9 board) or PCB or ((circuit$4 or wiring) near9 board))) and (((barium near9 titanate) or BaTiO) same (powder or paste or material or filler or capacitor) same particle same diameter same (polymer or resin or epoxy) same (fine near9 (powder or particle or size or diameter)))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
16	4	(((print$4 near9 (wiring or circuit$4) near9 board) or PCB or ((circuit$4 or wiring) near9 board))) and (((barium near9 titanate) or BaTiO) same (powder or paste or material or filler or capacitor) same (coarse or particle or size) same diameter same (polymer or resin or epoxy) same (fine near9 (powder or particle or size or diameter)))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
17	6	(((print$4 near9 (wiring or circuit$4) near9 board) or PCB or ((circuit$4 or wiring) near9 board))) and (((barium near9 titanate) or BaTiO) same (coarse or particle or size) same diameter same (polymer or resin or epoxy or PTFE) same (fine near9 (powder or particle or size or diameter)))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
18	0	(((print$4 near9 (wiring or circuit$4) near9 board) or PCB or ((circuit$4 or wiring) near9 board))) and (((barium near9 titanate) or BaTiO) same (coarse or particle or size) same diameter same (fine near9 (powder or particle or size or diameter))) and (((barium near9 titanate) or BaTiO) same (capacitor or (passive near9 element)) same (epoxy or polymer or PTFE or (thermosetting near9 resin) or resin$4))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
19	6	(((print$4 near9 (wiring or circuit$4) near9 board) or PCB or ((circuit$4 or wiring) near9 board))) and (((barium near9 titanate) or BaTiO) same (coarse or particle or size) same diameter same (fine near9 (powder or particle or size or diameter))) and (((barium near9 titanate) or BaTiO) same (epoxy or polymer or PTFE or (thermosetting near9 resin) or resin$4))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
20	6	(((print$4 near9 (wiring or circuit$4) near9 board) or PCB or ((circuit$4 or wiring) near9 board))) and (((barium near9 titanate) or BaTiO$2) same (coarse or particle or size) same diameter same (fine near9 (powder or particle or size or diameter))) and (((barium near9 titanate) or BaTiO$3) same (epoxy or polymer or PTFE or (thermosetting near9 resin) or resin$4))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
21	58	(((print$4 near9 (wiring or circuit$4) near9 board) or PCB or ((circuit$4 or wiring) near9 board))) and (((barium near9 titanate) or BaTiO$2) same (coarse or particle) same (size or diameter)) and (((barium near9 titanate) or BaTiO$3) same (epoxy or polymer or PTFE or (thermosetting near9 resin) or resin$4) same particle same (diameter or micron or nanometer or nm))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB